

3-24-05

04-07-2005



Atty Docket No. TSM04-0352

To the Director of the U.S. Pa...

102974504

Documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Wai-Yi Lien
Denny Duan-lee Tang

2. Name and address of receiving party(ies)
Name: Taiwan Semiconductor Manufacturing Company, Ltd.
Internal Address: _____

Execution Date(s) March 24, 2005
Additional name(s) of conveying party(ies) attached? Yes No

Street Address: No. 8, Li-Hsin Rd. 6
Science-Based Industrial Park
City: Hsin-Chu
State: Taiwan
Country: ROC Zip: 300-77

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):
A. Patent Application No.(s) _____
B. Patent No.(s) _____

This document is being filed together with a new application.
Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:
Name: Steven H. Slater
Slater & Matsil, L.L.P.
Internal Address: _____
Street Address: 17950 Preston Rd.
Suite 1000
City: Dallas
State: Texas Zip: 75252-5793
Phone Number: 972-732-1001
Fax Number: 972-732-9218
Email Address: slater@slater-matsil.com

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

04/06/2005 BY:RME 00000233 501065 11089186
01 FC:002 40.00 BA

8. Payment Information
a. Credit Card Last 4 Numbers _____
Expiration Date _____
b. Deposit Account Number 50-1065
Authorized User Name Steven H. Slater

9. Signature: Steven H. Slater
Signature _____
Steven H. Slater, Reg. No. 35,361
Name of Person Signing

March 24, 2005
Date
Total number of pages including cover sheet, attachments, and documents: 2

112959 U.S. PTO
11/089186



032405

ATTORNEY DOCKET NO. TSM04-0352

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

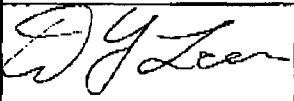
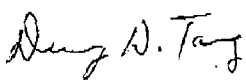
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

TITLE OF INVENTION	<i>Method and Structure for Isolating Substrate Noise</i>		
SIGNATURE OF INVENTOR AND NAME	 Wai-Yi Lien	 Denny Duan-lee Tang	
DATE	<i>Mar. 24, 2005</i>	<i>2005, 03-24</i>	
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan R.O.C.	Saratoga, CA US	